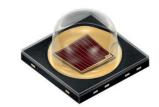
OSLON® Black

OSLON Black Series combines thermal stability with high performance and reliability in a compact black package. It has a metal lead frame and a tried and tested lens design. The LED can be used wherever there are large fluctuations in temperature and a large amount of light is needed from a small area.





Applications

- Cluster, Button Backlighting
- Custom Tuning
- Head-Up Display LED & Laser

- Interior Illumination e.g. Ambient Map
- Transportation, Plane, Ship

Features:

- Package: SMD epoxy package with silicone lens
- Chip technology: Thinfilm
- Typ. Radiation: 90°
- Color: $\lambda_{dom} = 590 \text{ nm}$ (• yellow)
- Corrosion Robustness Class: 3B
- Qualifications: The product qualification test plan is based on the guidelines of AEC-Q101-REV-C,
 Stress Test Qualification for Automotive Grade Discrete Semiconductors.
- ESD: 8 kV acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 3B)



Ordering Information		
Туре	Luminous Flux $^{1)}$ I _F = 350 mA Φ_{V}	Ordering Code
LY H9GP-HZKY-36-1	39 97 lm	Q65111A7367



Maximum Ratings			
Parameter	Symbol		Values
Operating Temperature	T _{op}	min. max.	-40 °C 125 °C
Storage Temperature	T _{stg}	min. max.	-40 °C 125 °C
Junction Temperature	T _j	max.	150 °C
Junction Temperature for short time applications*	T _j	max.	175 °C
Forward current T _S = 25 °C	I _F	min. max.	100 mA 1000 mA
Surge Current $t \le 10 \ \mu s; \ D = 0.016 \ ; \ T_s = 25 \ ^{\circ}C$	I _{FS}	max.	2500 mA
ESD withstand voltage acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 3B)	V _{ESD}		8 kV
Reverse current 2)	I _R	max.	200 mA

^{*}The median lifetime (L70/B50) for Tj =175 $^{\circ}$ C is 100h.



Characteristics

 I_F = 350 mA; T_S = 25 °C

Parameter	Symbol		Values
Peak Wavelength	λ_{peak}	typ.	597 nm
Dominant Wavelength 3)	$\lambda_{\sf dom}$	min.	583 nm
$I_{\rm F} = 350 \text{mA}$	dom	typ.	590 nm
•		max.	595 nm
Spectral Bandwidth at 50% I _{rel,max}	Δλ	typ.	18 nm
Viewing angle at 50 % I _V	2φ	typ.	90 °
Forward Voltage 4)	V_{F}	min.	2.05 V
$I_{\rm F} = 350 \text{mA}$	·	typ.	2.26 V
		max.	2.65 V
Reverse voltage (ESD device)	V _{R ESD}	min.	45 V
Reverse voltage ²⁾ I _R = 20 mA	V_R	max.	1.2 V
Real thermal resistance junction/solderpoint 5)	R _{thJS real}	typ.	6.5 K / W
	1100 1641	max.	11.0 K / W



Brightness Groups

Group	Luminous Flux ¹⁾ $I_F = 350 \text{ mA}$ min. Φ_V	Luminous Flux ¹⁾ $I_F = 350 \text{ mA}$ max. Φ_V	Luminous Intensity $^{6)}$ I _F = 350 mA typ. I _v
HZ	39 lm	45 lm	21 cd
JX	45 lm	52 lm	24 cd
JY	52 lm	61 lm	28 cd
JZ	61 lm	71 lm	33 cd
KX	71 lm	82 lm	38 cd
KY	82 lm	97 lm	44 cd

Forward Voltage Groups

Group	Forward Voltage 4)	Forward Voltage 4)	
	$I_{F} = 350 \text{ mA}$	$I_F = 350 \text{ mA}$	
	min.	max.	
	V_{F}	V_{F}	
9B	2.05 V	2.35 V	
9C	2.35 V	2.65 V	

Wavelength Groups

Group	Dominant Wavelength 3)	Dominant Wavelength 3)
	$I_{F} = 350 \text{ mA}$	$I_F = 350 \text{ mA}$
	min.	max.
	$\lambda_{\sf dom}$	$\lambda_{\sf dom}$
3	583 nm	586 nm
4	586 nm	589 nm
5	589 nm	592 nm
6	592 nm	595 nm



Group Name on Label

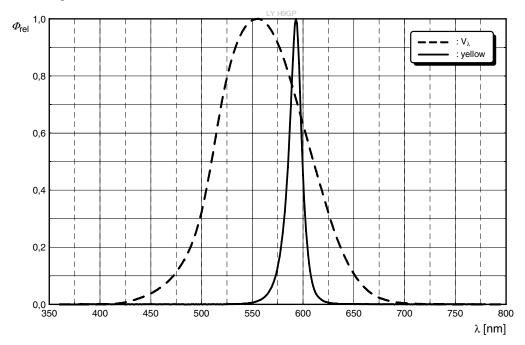
Example: HZ-3-9B

Brightness	Wavelength	Forward Voltage
HZ	3	9B



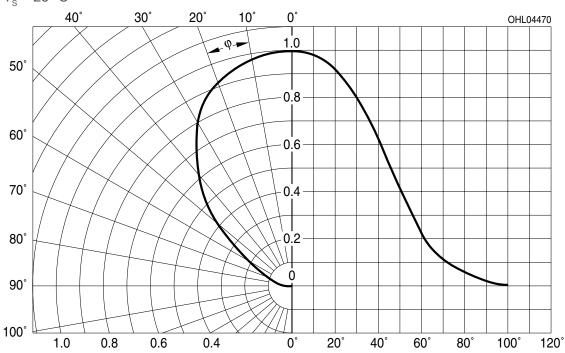
Relative Spectral Emission 6)

$$\Phi_{rel}$$
 = f (λ); I_F = 350 mA; T_S = 25 °C



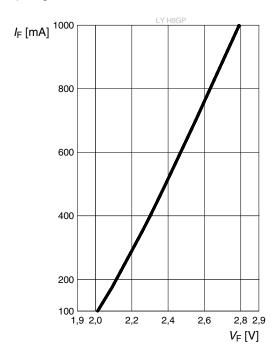
Radiation Characteristics 6)

$$I_{rel} = f (\phi); T_S = 25 \, ^{\circ}C$$



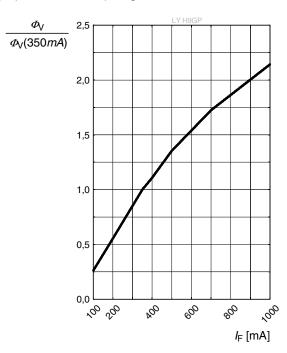
Forward current 6), 7)

$$I_F = f(V_F); T_S = 25 \, ^{\circ}C$$



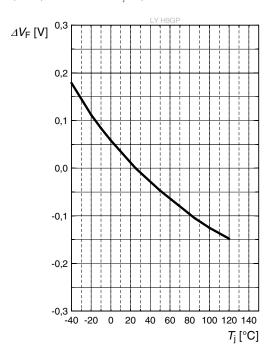
Relative Luminous Flux 6), 7)

$$\Phi_{V}/\Phi_{V}(350 \text{ mA}) = f(I_{F}); T_{S} = 25 \text{ °C}$$



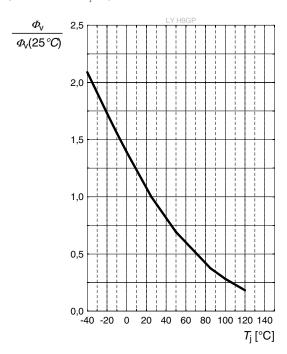
Forward Voltage 6)

$$\Delta V_F = V_F - V_F (25 \ ^{\circ}C) = f(T_j); I_F = 350 \ mA$$



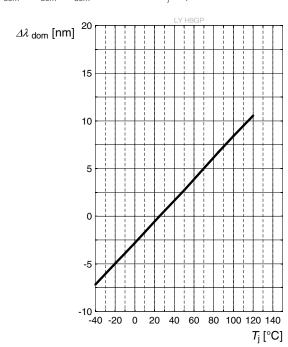
Relative Luminous Flux 6)

$$\Phi_{V}/\Phi_{V}(25 \text{ °C}) = f(T_{i}); I_{F} = 350 \text{ mA}$$



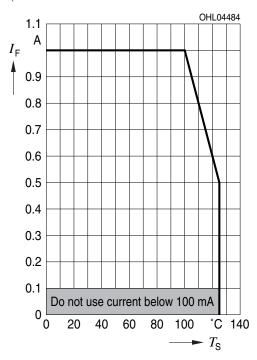
Dominant Wavelength 6)

$$\Delta \lambda_{dom} = \lambda_{dom} - \lambda_{dom} (25 \ ^{\circ}C) = f(T_{j}); \ I_{F} = 350 \ mA$$



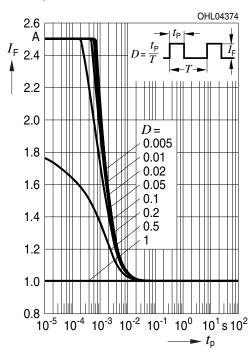
Max. Permissible Forward Current

 $I_{\scriptscriptstyle F} = f(T)$



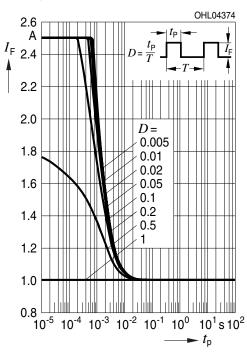
Permissible Pulse Handling Capability

 $I_F = f(t_p)$; D: Duty cycle; $T_S = 25 \, ^{\circ}C$

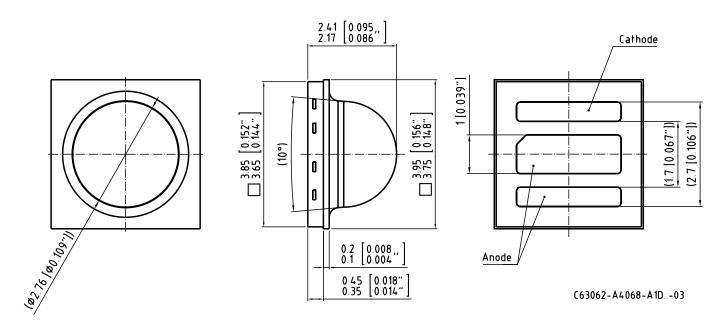


Permissible Pulse Handling Capability

 $I_{_{\rm F}}$ = f(t $_{_{
m D}}$); D: Duty cycle; $T_{_{
m S}}$ = 85 °C



Dimensional Drawing 8)



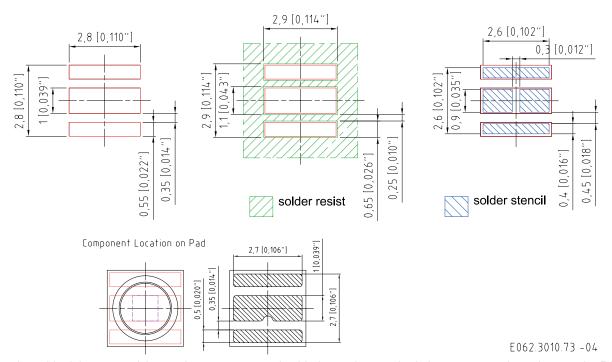
Approximate Weight:32.0 mgPackage marking:CathodeCorrosion test:Class: 3B

Test condition: 40° C / 90 % RH / 15 ppm H₂S / 14 days (stricter then IEC

60068-2-43)

ESD advice: LED is protected by ESD device which is connected in paralell to LED-Chip.

Recommended Solder Pad 8)

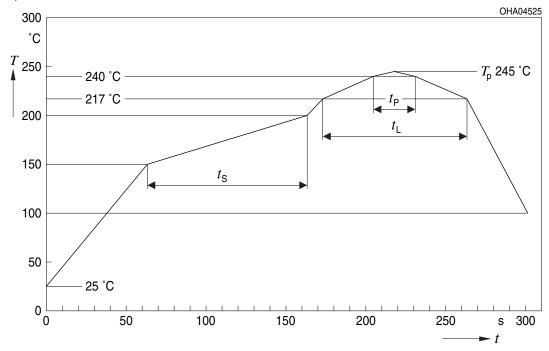


For superior solder joint connectivity results we recommend soldering under standard nitrogen atmosphere. In case the PCB layout of the application is intended to be used with other OSLON derivates or in future developed OSLON derivates, the heat sink must not be electrically connected to anode or cathode solder pad because of possible chip inverted polarity. Package not suitable for ultra sonic cleaning.



Reflow Soldering Profile

Product complies to MSL Level 2 acc. to JEDEC J-STD-020E

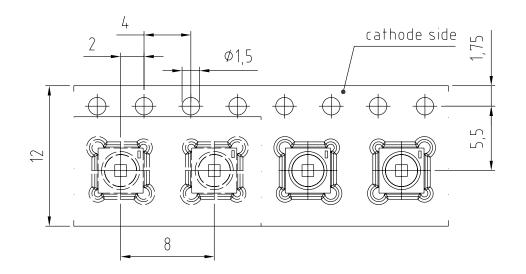


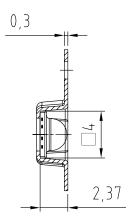
Profile Feature	Symbol	Pb	-Free (SnAgCu) Ass	nAgCu) Assembly	
		Minimum	Recommendation	Maximum	
Ramp-up rate to preheat*) 25 °C to 150 °C			2	3	K/s
Time t_s T_{Smin} to T_{Smax}	t _s	60	100	120	S
Ramp-up rate to peak*) $T_{\rm Smax}$ to $T_{\rm P}$			2	3	K/s
Liquidus temperature	T_L		217		°C
Time above liquidus temperature	$t_{\scriptscriptstyle \perp}$		80	100	S
Peak temperature	T _P		245	260	°C
Time within 5 °C of the specified peak temperature T _p - 5 K	t _P	10	20	30	S
Ramp-down rate* T _P to 100 °C			3	6	K/s
Time 25 °C to T _P				480	S

All temperatures refer to the center of the package, measured on the top of the component * slope calculation DT/Dt: Dt max. 5 s; fulfillment for the whole T-range



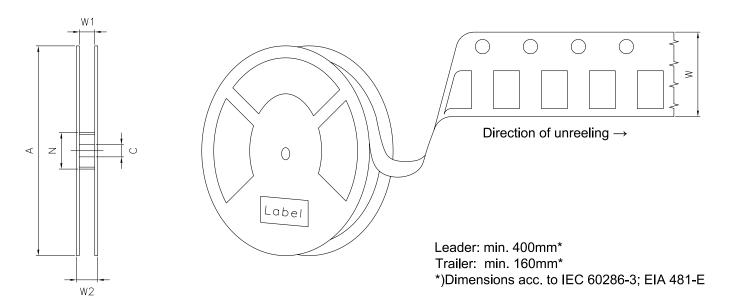
Taping 8)





C63062-A4068-B10 -12

Tape and Reel 9)



Reel dimensions [mm]

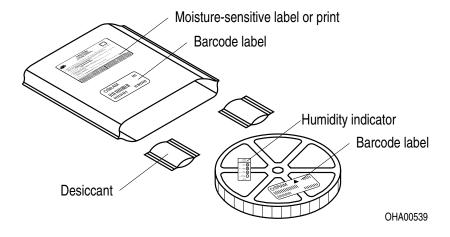
Α	W	N_{\min}	W ₁	$W_{2\mathrm{max}}$	Pieces per PU
180 mm	12 + 0.3 / - 0.1	60	12.4 + 2	18.4	600
330 mm	12 + 0.3 / - 0.1	60	12.4 + 2	18.4	3000



Barcode-Product-Label (BPL)



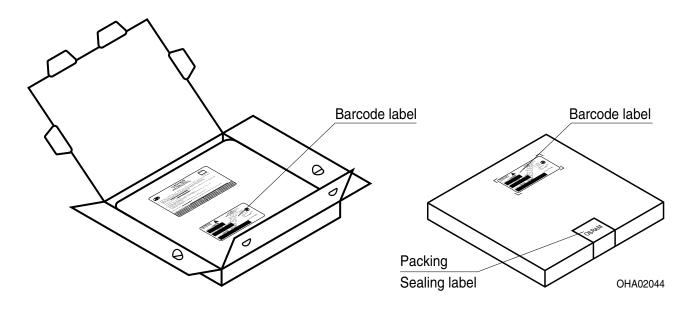
Dry Packing Process and Materials 8)



Moisture-sensitive product is packed in a dry bag containing desiccant and a humidity card according JEDEC-STD-033.



Transportation Packing and Materials 8)

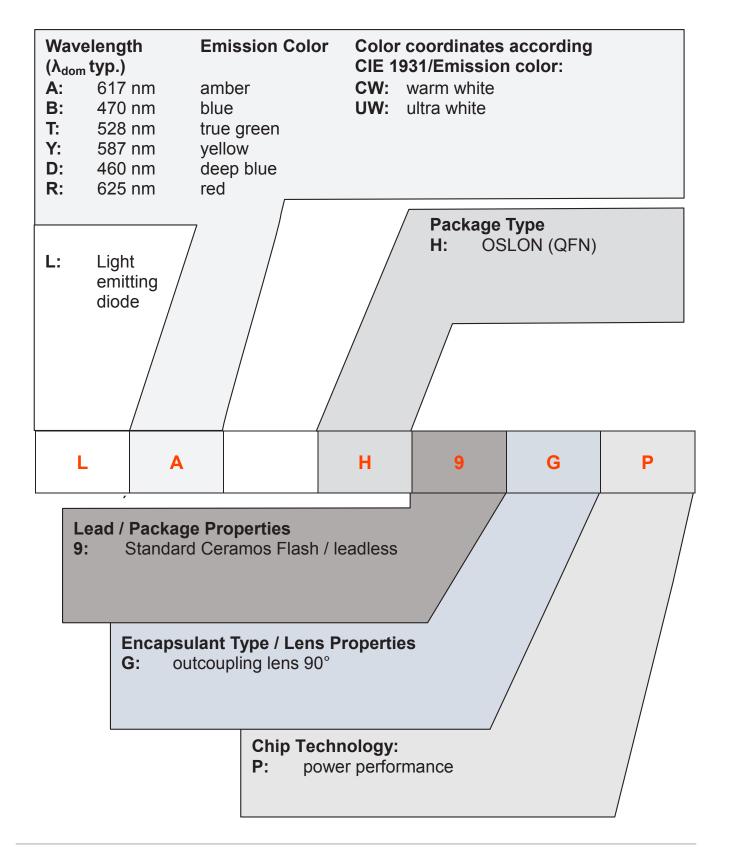


Dimensions of transportation box in mm

Width	Length	Height
195 ± 5 mm	195 ± 5 mm	30 ± 5 mm
349 ± 5 mm	349 ± 5 mm	33 ± 5 mm



Type Designation System



Notes

The evaluation of eye safety occurs according to the standard IEC 62471:2006 (photo biological safety of lamps and lamp systems). Within the risk grouping system of this IEC standard, the LED specified in this data sheet fall into the class exempt group (exposure time 10000 s). Under real circumstances (for exposure time, conditions of the eye pupils, observation distance), it is assumed that no endangerment to the eye exists from these devices. As a matter of principle, however, it should be mentioned that intense light sources have a high secondary exposure potential due to their blinding effect. When looking at bright light sources (e.g. headlights), temporary reduction in visual acuity and afterimages can occur, leading to irritation, annoyance, visual impairment, and even accidents, depending on the situation.

Subcomponents of this LED contain, in addition to other substances, metal filled materials including silver. Metal filled materials can be affected by environments that contain traces of aggressive substances. Therefore, we recommend that customers minimize LED exposure to aggressive substances during storage, production, and use. LEDs that showed visible discoloration when tested using the described tests above did show no performance deviations within failure limits during the stated test duration. Respective failure limits are described in the IEC60810.

For further application related informations please visit www.osram-os.com/appnotes



Disclaimer

Disclaimer

Language english will prevail in case of any discrepancies or deviations between the two language wordings.

Attention please!

The information describes the type of component and shall not be considered as assured characteristics. Terms of delivery and rights to change design reserved. Due to technical requirements components may contain dangerous substances.

For information on the types in question please contact our Sales Organization.

If printed or downloaded, please find the latest version on the OSRAM OS webside.

Packing

Please use the recycling operators known to you. We can also help you – get in touch with your nearest sales office.

By agreement we will take packing material back, if it is sorted. You must bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.

Product safety devices/applications or medical devices/applications

OSRAM OS components are not developed, constructed or tested for the application as safety relevant component or for the application in medical devices.

In case Buyer - or Customer supplied by Buyer- considers using OSRAM OS components in product safety devices/applications or medical devices/applications, Buyer and/or Customer has to inform the local sales partner of OSRAM OS immediately and OSRAM OS and Buyer and /or Customer will analyze and coordinate the customer-specific request between OSRAM OS and Buyer and/or Customer.



Glossary

- Brightness: Brightness values are measured during a current pulse of typically 25 ms, with an internal reproducibility of ±8 % and an expanded uncertainty of ±11 % (acc. to GUM with a coverage factor of
- Reverse Operation: Reverse Operation of 10 hours is permissible in total. Continuous reverse operation is not allowed.
- 3) Wavelength: The wavelength is measured at a current pulse of typically 25 ms, with an internal reproducibility of ±0.5 nm and an expanded uncertainty of ±1 nm (acc. to GUM with a coverage factor of k = 3).
- Forward Voltage: The forward voltage is measured during a current pulse of typically 8 ms, with an internal reproducibility of ±0.05 V and an expanded uncertainty of ±0.1 V (acc. to GUM with a coverage factor of k = 3).
- 5) **Thermal Resistance**: Rth max is based on statistic values (6σ).
- 6) Typical Values: Due to the special conditions of the manufacturing processes of LED, the typical data or calculated correlations of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data and calculated correlations or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.
- Characteristic curve: In the range where the line of the graph is broken, you must expect higher differences between single LEDs within one packing unit.
- Tolerance of Measure: Unless otherwise noted in drawing, tolerances are specified with ±0.1 and dimensions are specified in mm.
- Tape and Reel: All dimensions and tolerances are specified acc. IEC 60286-3 and specified in mm.



Published by OSRAM Opto Semiconductors GmbH EU RoHS and China RoHS compliant product Leibnizstraße 4, D-93055 Regensburg www.osram-os.com © All Rights Reserved.

此产品符合欧盟 RoHS 指令的要求; 按照中国的相关法规和标准,不含有毒有害物质或元素。

